MA3J745EG

Silicon epitaxial planar type

For high speed switching For wave detection

■ Features

- Two elements are contained in one package, allowing highdensity mounting
- \bullet Low forward voltage $\boldsymbol{V}_{\boldsymbol{F}}$, optimum for low voltage rectification
- Optimum for high frequency rectification because of its short reverse recovery time t_{rr}

■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter		Symbol	Rating	Unit	
Reverse voltage		V _R	30	V	
Maximum peak reverse voltage		V_{RM}	30	V	
Forward current	Single	I_{F}	30	mA	
	Double		20		
Peak forward current	Single	T	150	mA	
	Double	I_{FM}	110		
Junction temperature		T _j	125	°C	
Storage time		T_{stg}	-55 to +125	€°C	

■ Package

• Code

SMini3-F2

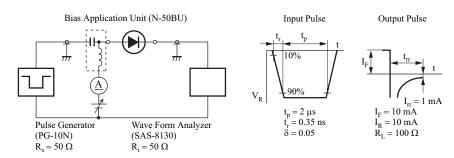
- Pin Name
 - 1: Anode 1
 - 2: Anode 2
 - 3: Cathode
- Marking Symbol: M3D
- Internal Connection



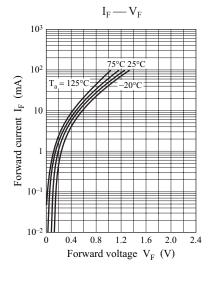
■ Electrical Characteristics $T_a = 25$ °C±3°C

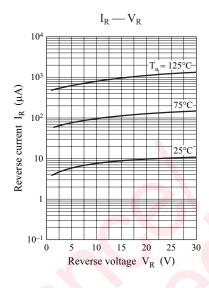
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage	V_{F1}	$I_F = 1 \text{ mA}$	5,00		0.3	V
	V_{F2}	$I_F = 30 \text{ mA}$			1.0	
Reverse current	I_R	$V_R = 30 \text{ V}$.; 0		30	μΑ
Terminal capacitance	C_{t}	$V_R = 1 \text{ V, } f = 1 \text{ MHz}$		1.5		pF
Reverse recovery time *	t _{rr}	$\begin{split} I_F = I_R = 100 \text{ mA}, \ I_{rr} = 10 \text{ mA}, \\ R_L = 100 \ \Omega \end{split}$		1.0		ns
Detection efficiency	η	$V_{IN} = 3 V_{(peak)}$, f = 30 MHz R _L = 3.9 k Ω , C _L = 10 pF		65		%

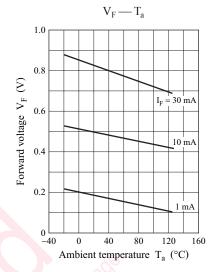
- Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.
 - 2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.
 - 3. Absolute frequency of input and output is $2\ \mbox{GHz}$
 - 4. *: t_{rr} measurement circuit

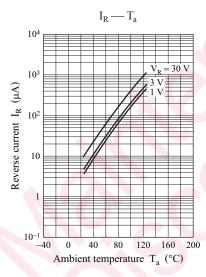


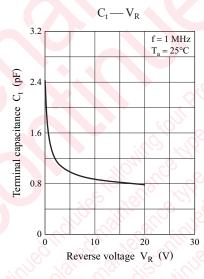
MA3J745EG Panasonic

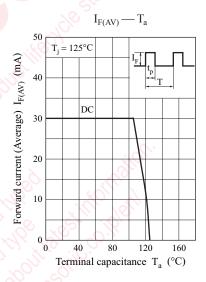






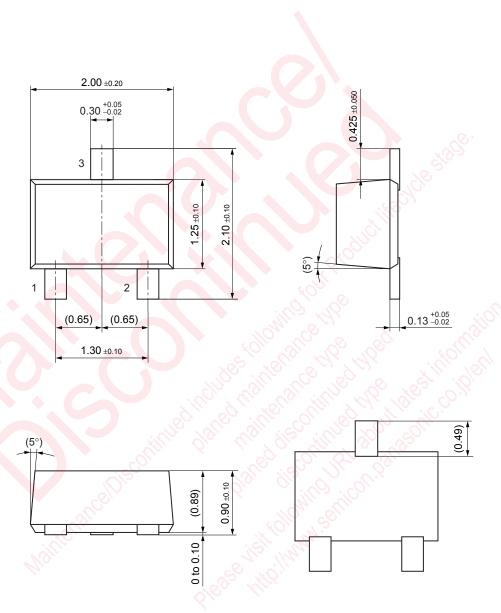






Panasonic MA3J745EG

SMini3-F2 Unit: mm



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